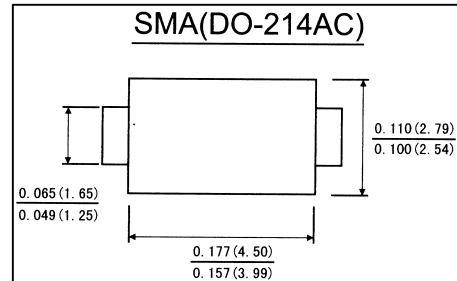


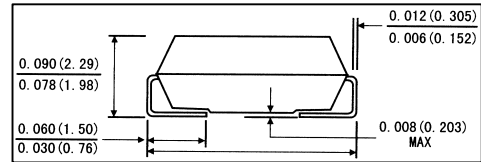
FEATURES

- . For surface mounted applications
- . Glass passivated junction
- . Low profile package
- . Built-in strain relief , ideal for automated placement
- . Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- . High temperature soldering guaranteed: 250°C/10 seconds, at terminals



MECHANICAL DATA

- . **Case:** JEDEC SMA(DO-214AC) molded plastic
- . **Terminals:** Plated axial leads,solderable per MIL-STD-750,method 2026
- . **Polarity:** Color band denotes cathode end
- . **Mounting Position:** Any
- . **Weight:** 0.002 ounce, 0.064 gram



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25°C ambient temperature unless otherwise specified,Single phase,half wave 60Hz,resistive or inductive)

load. For capacitive load,derate current by 20%)

	Symbols	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Units
Maximum Recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum average forward rectified current (See fig.1)	I _(AV)	1.0							Amp
Peak forward surge current (8.3ms half sing wave superimposed on rated load (JEDEC method)T _L =110°C	I _{FSM}	40.0			30.0			Amps	
Maximum instantaneous forward voltage at 1.0 A	V _F	1.1							Volts
Maximum reverse recovery time(Note 1) current at rated DC Blocking Voltage	I _R	T _A =25°C	1.0			5.0			μ A
		T _A =125°C	50						
Typical Thermal Resistance(Note 1)	R _θ JL	27.0			30.0			°C/W	
	R _θ JA	25.0			85.0				
Typical reverse recovery time(Note 2)	T _{rr}	1.8							μ S
Operating and storage temperature range	T _J T _{STG}	-65 to +150							°C

Notes: 1.Thermal resistance from junction to ambient and from junction to lead mounted on 0.2 X 0.2"(5.0 X 5.0mm) copper pad areas.

2.Test conditions:IF=0.5A,IR=1.0A,Irr=0.25A.

RATINGS AND CHARACTERISTIC CURVES S1A THRU S1M

FIG.1-FORWARD CURRENT DERATING CURVE

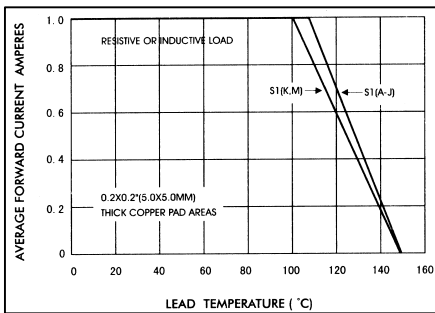


FIG.2-TYPICAL REVERSE CHARACTERISTICS

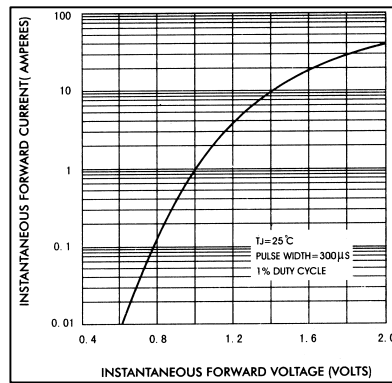


FIG.4-TYPICAL REVERSE CHARACTERISTICS

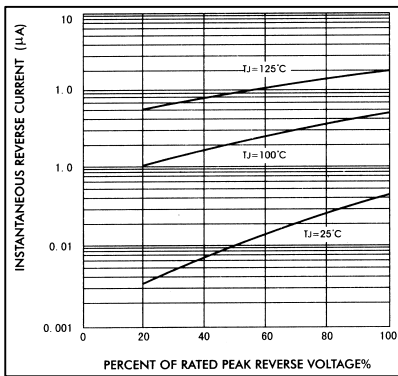


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

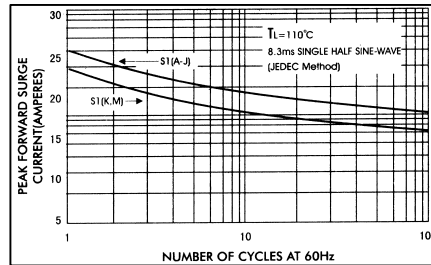


FIG.5-TYPICAL JUNCTION CAPACITANCE

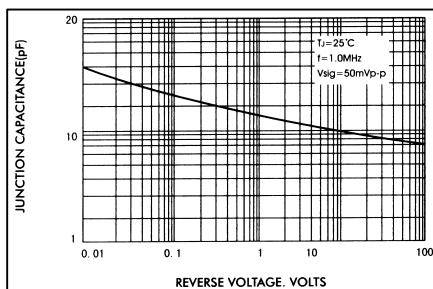


FIG.6-TYPICAL TRANSIENT THERMAL IMPEDANCE

